IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
PATENT APPLICATION

Appl. No.	:	TBD	Confirmation No. TBD
Applicant	:	Jan et al.	
Filed:	:	Herewith	
TC/A.U.	:	TBD	
Examiner	:	TBD	
Docket No.	:	TI-33949.1	
Customer No.	:	23494	

Mail Stop Patent Application
Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

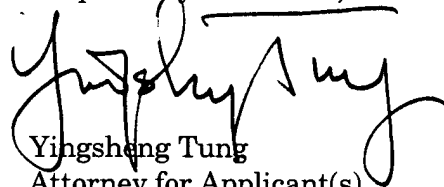## INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97 & 1.98

Sir:

Applicants wish to bring to the attention of the Patent and Trademark Office the information noted on the enclosed PTO Form 1449. Pursuant to the new rules, only copies of the non - U.S. Patents and Publications listed are enclosed.

Please charge any fees due in connection with the filing of this paper to the deposit account of Texas Instruments Incorporated, Account No. 20-0668. Please credit any excess fees to the same deposit account.

Respectfully submitted,

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FORM PTO-1449 (REV. 7-80) LIST OF DOCUMENTS CITED BY APPLICANT *(Use several sheets if necessary)*	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. **TI-33949.1**	SERIAL NO. **TBD**

	APPLICANT: **Jan et al.**	
	FILING DATE **Herewith**	GROUP **TBD**

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
		5,432,117	07/11/95	Yamamoto	437	69	05/23/1994
		5,726,092	03/10/98	Mathews et al.	438	439	05/23/1997
		5,780,352	07/14/98	Park et al.	438	404	10/23/1995

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	

OTHER NON-PATENT DOCUMENTS *(Including Author, Title, Date, Pertinent Pages, Etc.)*

		"A Viscous Nitride Model for Nitride/Oxide Isolation Structures", Griffin et al, IEDM 1990. pp 741-744

EXAMINER	DATE CONSIDERED

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.